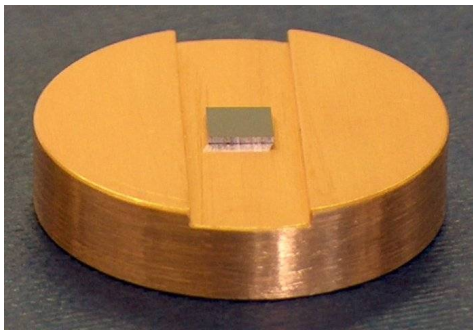
Glued SAM data sheet SAM-λ-A-τ-4.0-25.4g-c or 4.0-25.4g-e

GaAs chip area	standard:	4.0 mm x 4.0 mm
	optional:	other dimensions on request
Chip thickness	standard:	450 µm
Front side protection	the SAM is protected with a dielectric front layer.	

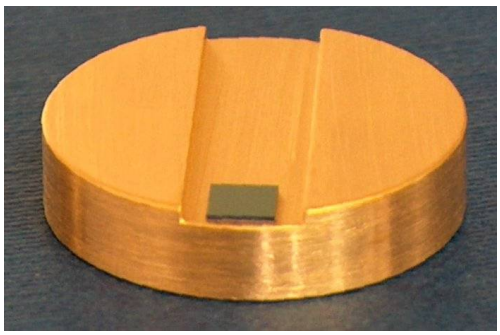
The SAM chip is glued on a gold plated Cu-cylinder with 25.4 mm Ø using a thermal conducting glue.

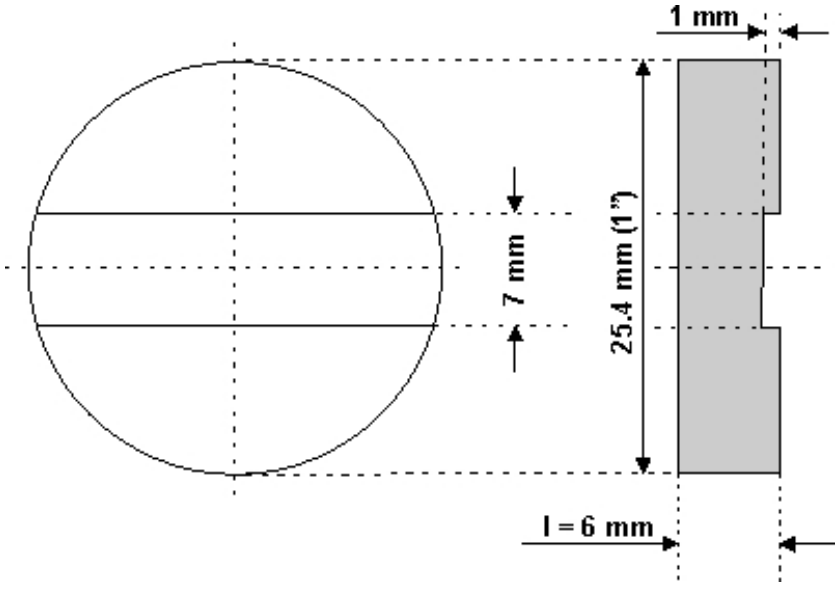
- The ***standard*** position of the SAM is at the center of the mount → x = 4.0-25.4g-c.
- ***Optional*** the SAM can be mounted at the edge of the mount without extra charges.
  → x = 4.0-25.4g-e.

Center mounted SAM



Edge mounted SAM



Mount

Cu-cylinder, ∅ = 25.4 mm
l = 6.0 mm